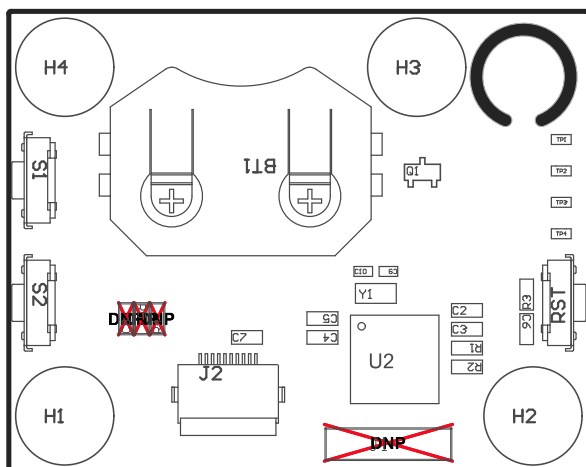


- Z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

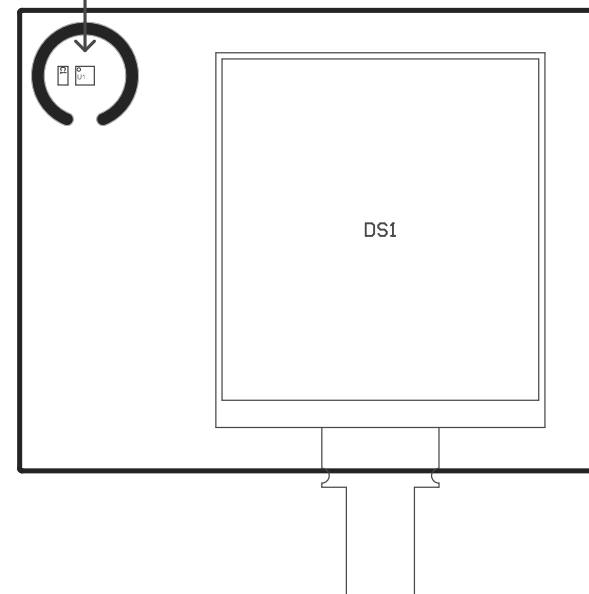
- Z24 ■ These assemblies must not be washed after the HDC device is mounted.
- Z25 ■ These assemblies must not have flux contamination between the HDC device and the PCB.
- Z26 ■ Recommended to assemble and wash top side components before assembling HDC on bottom side.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: SENS020	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-01625		
PLOT NAME = Top Assembly Drawing	GENERATED : 4/30/2018	2:05:35 PM	TEXAS INSTRUMENTS

HDC device must not be submerged in cleaning solution.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: SENS020	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-01625		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/30/2018	2:05:36 PM	TEXAS INSTRUMENTS

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